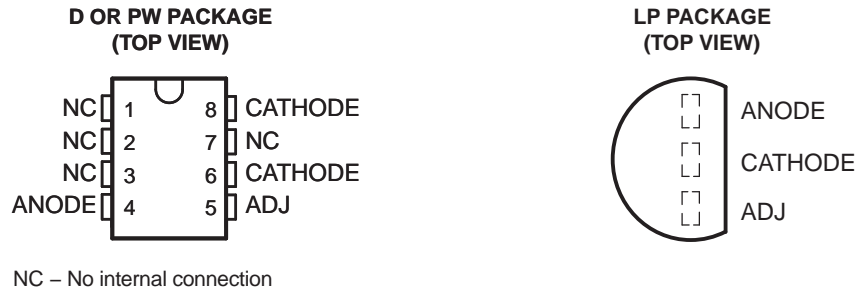


## 2.5-V INTEGRATED REFERENCE CIRCUIT

### FEATURES

- Excellent Temperature Stability
- Initial Tolerance: 0.2% Max
- Dynamic Impedance: 0.6  $\Omega$  Max
- Wide Operating Current Range
- Directly Interchangeable With LM136
- Needs No Adjustment for Minimum Temperature Coefficient



### DESCRIPTION/ORDERING INFORMATION

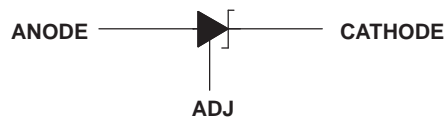
The LT1009 reference circuit is a precision-trimmed 2.5-V shunt regulator featuring low dynamic impedance and a wide operating current range. The maximum initial tolerance is  $\pm 5$  mV in the LP package and  $\pm 10$  mV in the D and PW packages. The reference tolerance is achieved by on-chip trimming, which minimizes the initial voltage tolerance and the temperature coefficient,  $\alpha_{VZ}$ .

Although the LT1009 needs no adjustments, a third terminal (ADJ) allows the reference voltage to be adjusted  $\pm 5\%$  to eliminate system errors. In many applications, the LT1009 can be used as a terminal-for-terminal replacement for the LM136-2.5, which eliminates the external trim network.

The LT1009 uses include 5-V system references, 8-bit analog-to-digital converter (ADC) and digital-to-analog converter (DAC) references, and power-supply monitors. The device also can be used in applications such as digital voltmeters and current-loop measurement and control systems.

The LT1009C is characterized for operation from 0°C to 70°C. The LT1009I is characterized for operation from –40°C to 85°C.

### SYMBOL



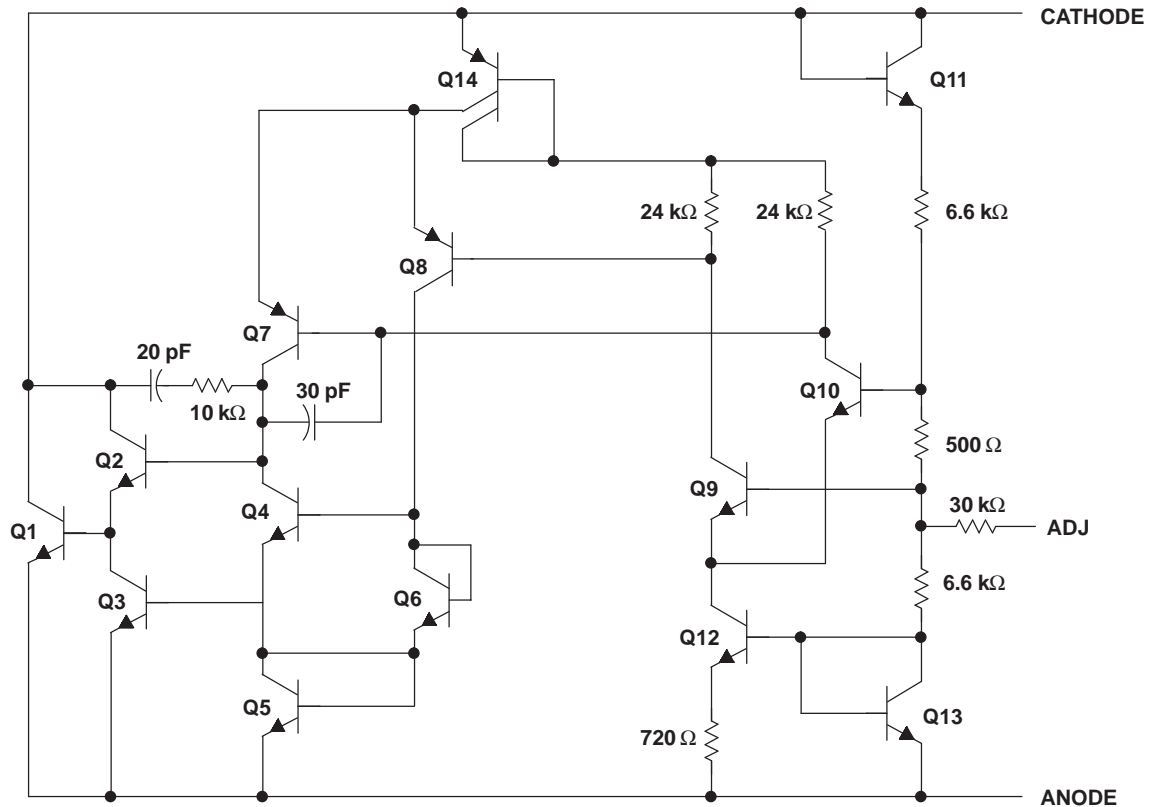
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**ORDERING INFORMATION<sup>(1)</sup>**

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	SOIC – D	Tube of 75	LT1009CD	1009C	
		Reel of 2500	LT1009CDR		
	TO-226/TO-92 – LP	Bulk of 1000	Ammo of 2000	LT1009CLP	LT1009C
			Reel of 2000	LT1009CLPR	
		TSSOP – PW	Tube of 150	LT1009CPW	
		Reel of 2000	LT1009CPWR		
–40°C to 85°C	SOIC – D	Tube of 75	LT1009ID	1009I	
		Reel of 2500	LT1009IDR		
	TO-226/TO-92 – LP	Bulk of 1000	Ammo of 2000	LT1009ILP	LT1009I
			Reel of 2000	LT1009ILPR	
		TSSOP – PW	Tube of 150	LT1009IPW	
		Reel of 2000	LT1009IPWR		

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).
- (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

**SCHEMATIC**



NOTE: All component values shown are nominal.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$I_R$	Reverse current		20	mA
$I_F$	Forward current		10	mA
$\theta_{JA}$	Package thermal impedance <sup>(2)(3)</sup>	D package	97	°C/W
		LP package	140	
		PW package	149	
$T_J$	Operating virtual junction temperature		150	°C
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Maximum power dissipation is a function of  $T_J(\text{max})$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

## RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT	
$T_A$	Operating free-air temperature range	LT1009C	0	70	°C
		LT1009I	–40	85	

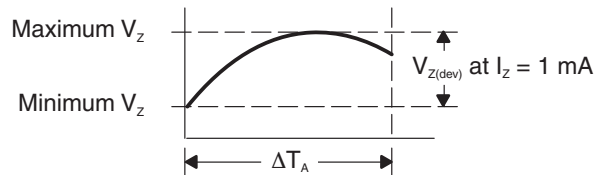
### ELECTRICAL CHARACTERISTICS

at specified free-air temperature

PARAMETER	TEST CONDITIONS	T <sub>A</sub> <sup>(1)</sup>	LT1009C			LT1009I			UNIT				
			MIN	TYP	MAX	MIN	TYP	MAX					
V <sub>Z</sub> Reference voltage	I <sub>Z</sub> = 1 mA	25°C	D/PW package		2.49	2.5	2.51	2.49	2.5	2.51	V		
			LP package		2.495	2.5	2.505	2.495	2.5	2.505			
		Full range	D/PW package		2.485		2.515		2.475			2.525	
			LP package		2.491		2.509		2.48			2.52	
V <sub>F</sub> Forward voltage	I <sub>F</sub> = 2 mA	25°C	0.4		1		0.4		1		V		
Adjustment range	I <sub>Z</sub> = 1 mA, V <sub>ADJ</sub> = GND to V <sub>Z</sub>	25°C	125		125		125		125		mV		
	I <sub>Z</sub> = 1 mA, V <sub>ADJ</sub> = 0.6 V to V <sub>Z</sub> - 0.6 V		45		45		45		45				
ΔV <sub>Z(temp)</sub> Change in reference voltage with temperature	D/PW package		Full range			5		15		mV			
	LP package		Full range			4		15					
αV <sub>Z</sub> Average temperature coefficient of reference voltage <sup>(2)</sup>	I <sub>Z</sub> = 1 mA, V <sub>ADJ</sub> = open	0°C to 70°C	15		25		15		25		ppm/°C		
		-40°C to 85°C					20		35				
ΔV <sub>Z</sub> Change in reference voltage with current	I <sub>Z</sub> = 400 μA to 10 mA	25°C	2.6		10		2.6		6		mV		
		Full range							10				
ΔV <sub>Z</sub> /Δt Long-term change in reference voltage	I <sub>Z</sub> = 1 mA	25°C	20		20		20		ppm/khr				
Z <sub>Z</sub> Reference impedance	I <sub>Z</sub> = 1 mA	25°C	0.3		1		0.3		1		Ω		
		Full range							1.4				

- (1) Full range is 0°C to 70°C for the LT1009C and -40°C to 85°C for the LT1009I.
- (2) The deviation parameter V<sub>Z(dev)</sub> is defined as the difference between the maximum and minimum values obtained over the recommended operating temperature range, measured at I<sub>Z</sub> = 1 mA. The average full-range temperature coefficient of the reference voltage (αV<sub>Z</sub>) is defined as:

$$|\alpha V_Z| \left( \frac{\text{ppm}}{^\circ\text{C}} \right) = \frac{\left( \frac{V_{Z(\text{dev})}}{V_Z \text{ at } 25^\circ\text{C}} \right) \times 10^6}{\Delta T_A}$$



αV<sub>Z</sub> can be positive or negative, depending upon whether the minimum V<sub>Z</sub> or maximum V<sub>Z</sub>, respectively, occurs at the lower temperature.

For example, at I<sub>Z</sub> = 1 mA, maximum V<sub>Z</sub> = 2501 mV at 30°C, minimum V<sub>Z</sub> = 2497 mV at 0°C, V<sub>Z</sub> = 2500 mV at 25°C, ΔT<sub>A</sub> = 70°C for LT1009C:

$$|\alpha V_Z| = \frac{\left( \frac{4 \text{ mV}}{2500 \text{ mV}} \right) \times 10^6}{70^\circ\text{C}} \approx 23 \frac{\text{ppm}}{^\circ\text{C}}$$

Because minimum V<sub>Z</sub> occurs at the lower temperature, the coefficient in this example is positive.

TYPICAL CHARACTERISTICS

Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

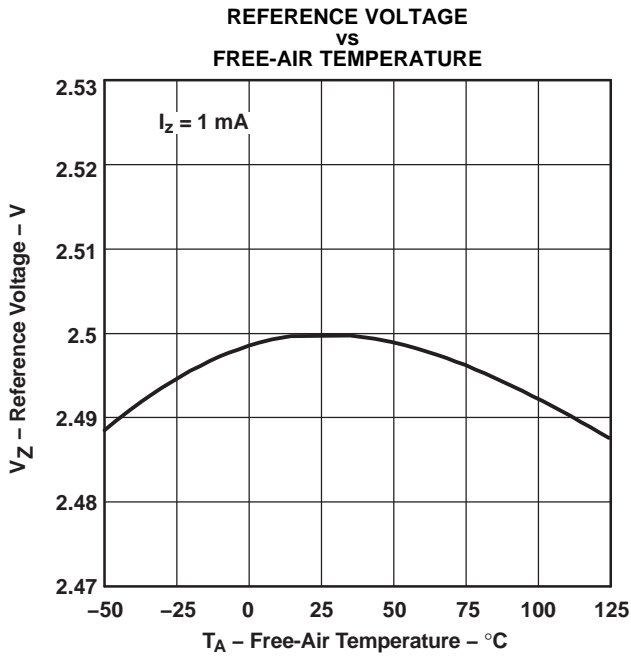


Figure 1.

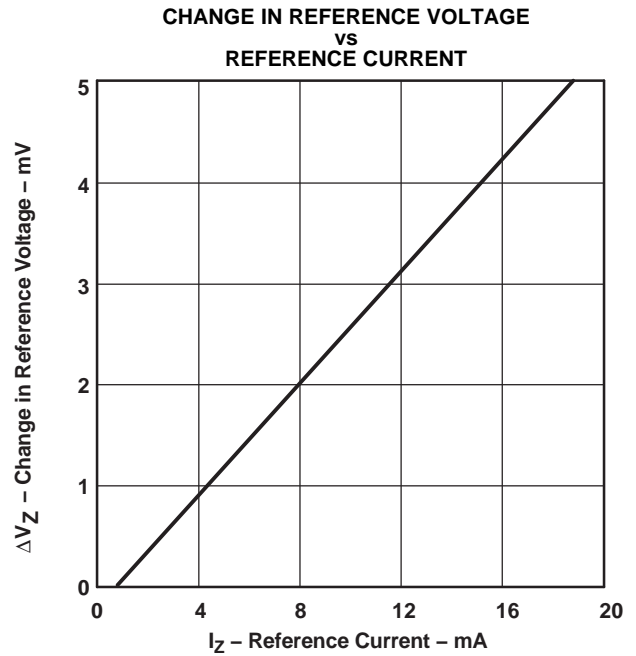


Figure 2.

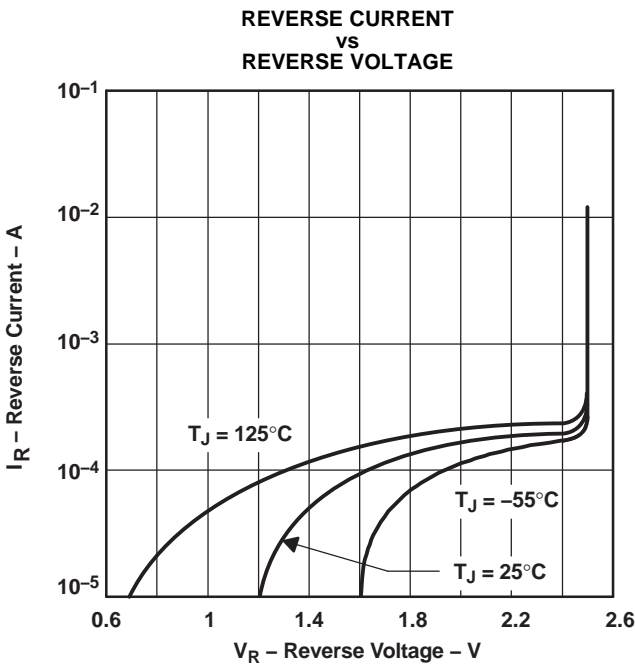


Figure 3.

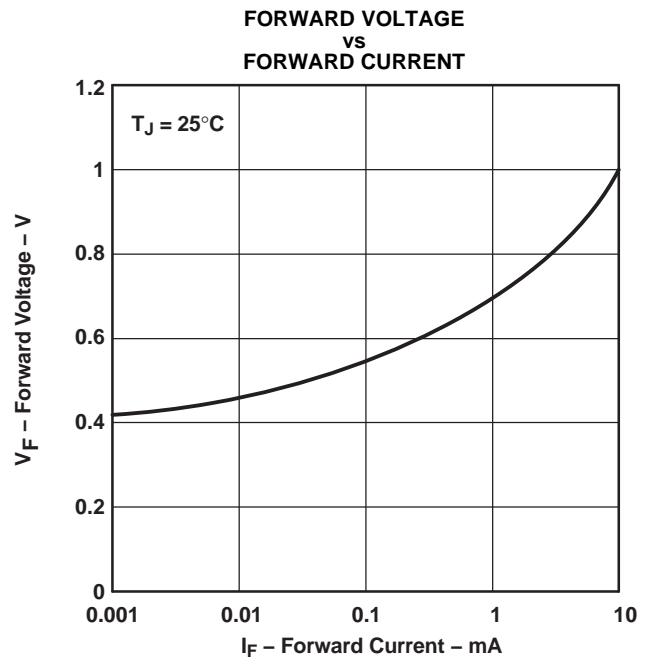


Figure 4.

TYPICAL CHARACTERISTICS (continued)

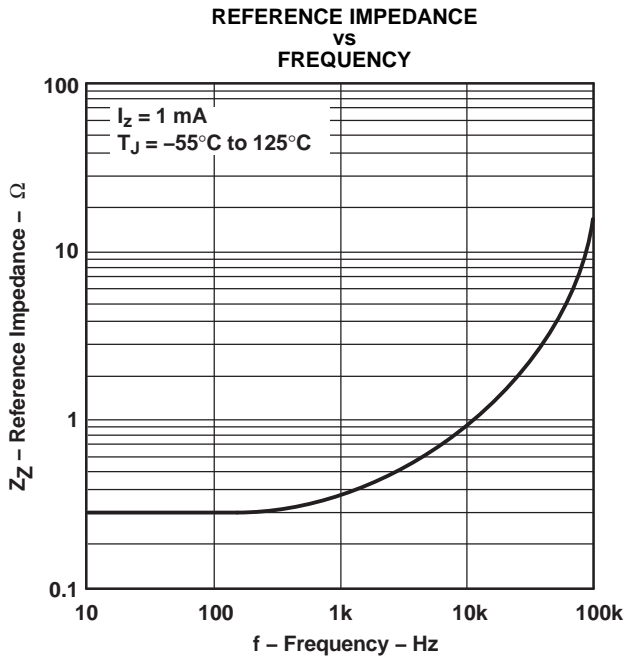


Figure 5.

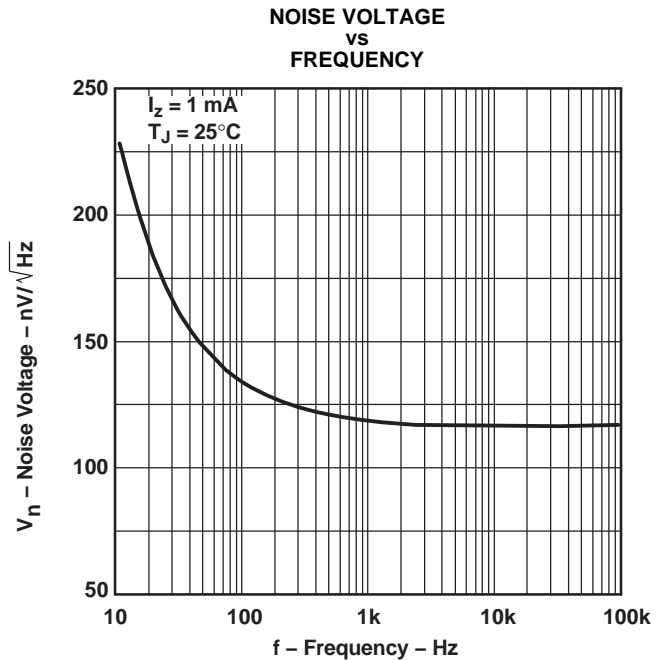


Figure 6.

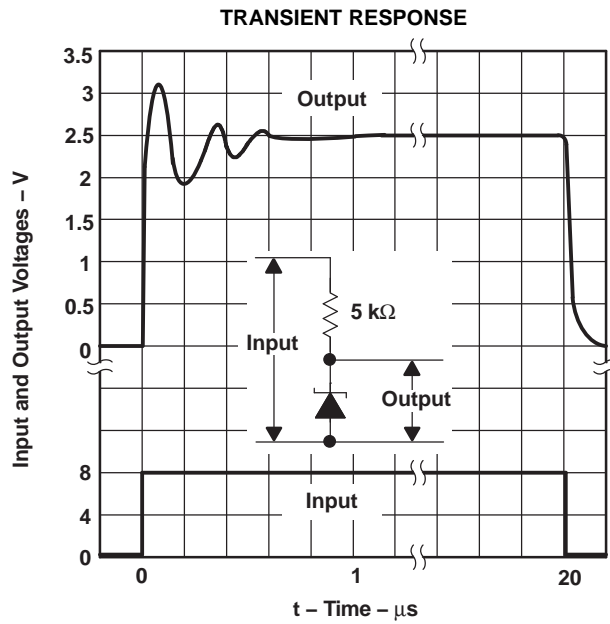
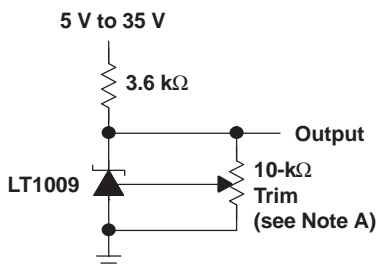


Figure 7.

APPLICATION INFORMATION



A. This does not affect temperature coefficient. It provides  $\pm 5\%$  trim range.

Figure 8. 2.5-V Reference

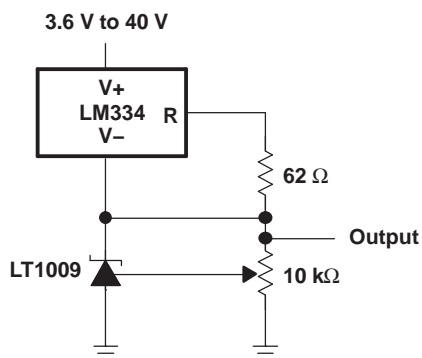


Figure 9. Adjustable Reference With Wide Supply Range

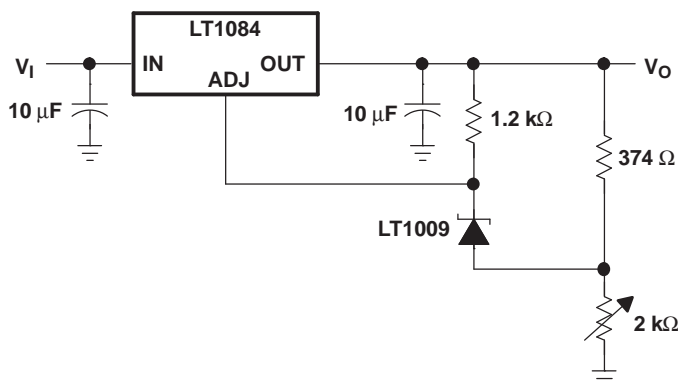


Figure 10. Power Regulator With Low Temperature Coefficient

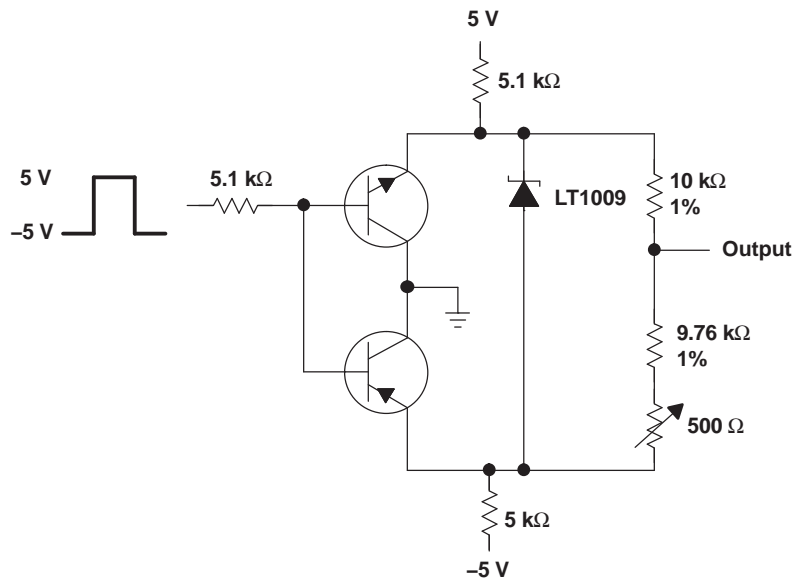


Figure 11. Switchable  $\pm 1.25\text{-V}$  Bipolar Reference

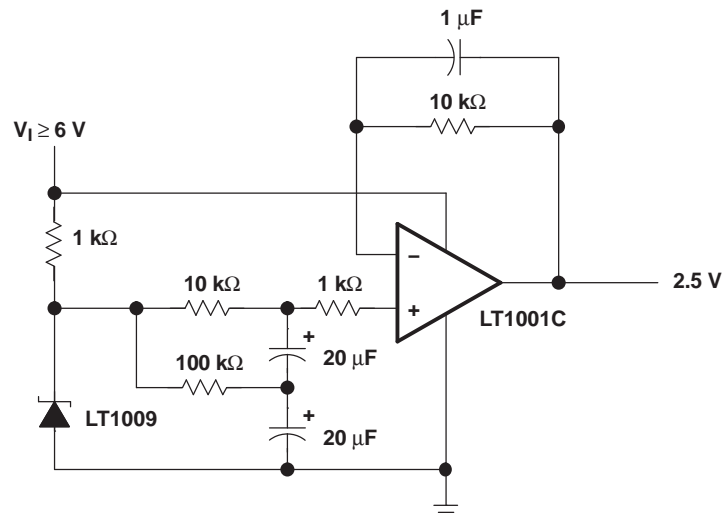


Figure 12. Low-Noise 2.5-V Buffered Reference



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LT1009CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	1009C	<a href="#">Samples</a>
LT1009CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	1009C	<a href="#">Samples</a>
LT1009CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	1009C	<a href="#">Samples</a>
LT1009CLP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LT1009C	<a href="#">Samples</a>
LT1009CLPE3	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LT1009C	<a href="#">Samples</a>
LT1009CLPM	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LT1009C	<a href="#">Samples</a>
LT1009CLPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LT1009C	<a href="#">Samples</a>
LT1009CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	1009C	<a href="#">Samples</a>
LT1009ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	1009I	<a href="#">Samples</a>
LT1009IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	1009I	<a href="#">Samples</a>
LT1009ILP	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	LT1009I	<a href="#">Samples</a>
LT1009ILPR	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	LT1009I	<a href="#">Samples</a>
LT1009ILPRE3	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	-40 to 85	LT1009I	<a href="#">Samples</a>
LT1009IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	1009I	<a href="#">Samples</a>
LT1009IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	1009I	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

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**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF LT1009 :**

- Military: [LT1009M](#)

NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LT1009CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1009CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LT1009IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LT1009IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LT1009CDR	SOIC	D	8	2500	340.5	338.1	20.6
LT1009CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LT1009IDR	SOIC	D	8	2500	340.5	338.1	20.6
LT1009IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW0008A



# PACKAGE OUTLINE

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

### NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

# EXAMPLE BOARD LAYOUT

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:10X



SOLDER MASK DETAILS  
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

LP 3

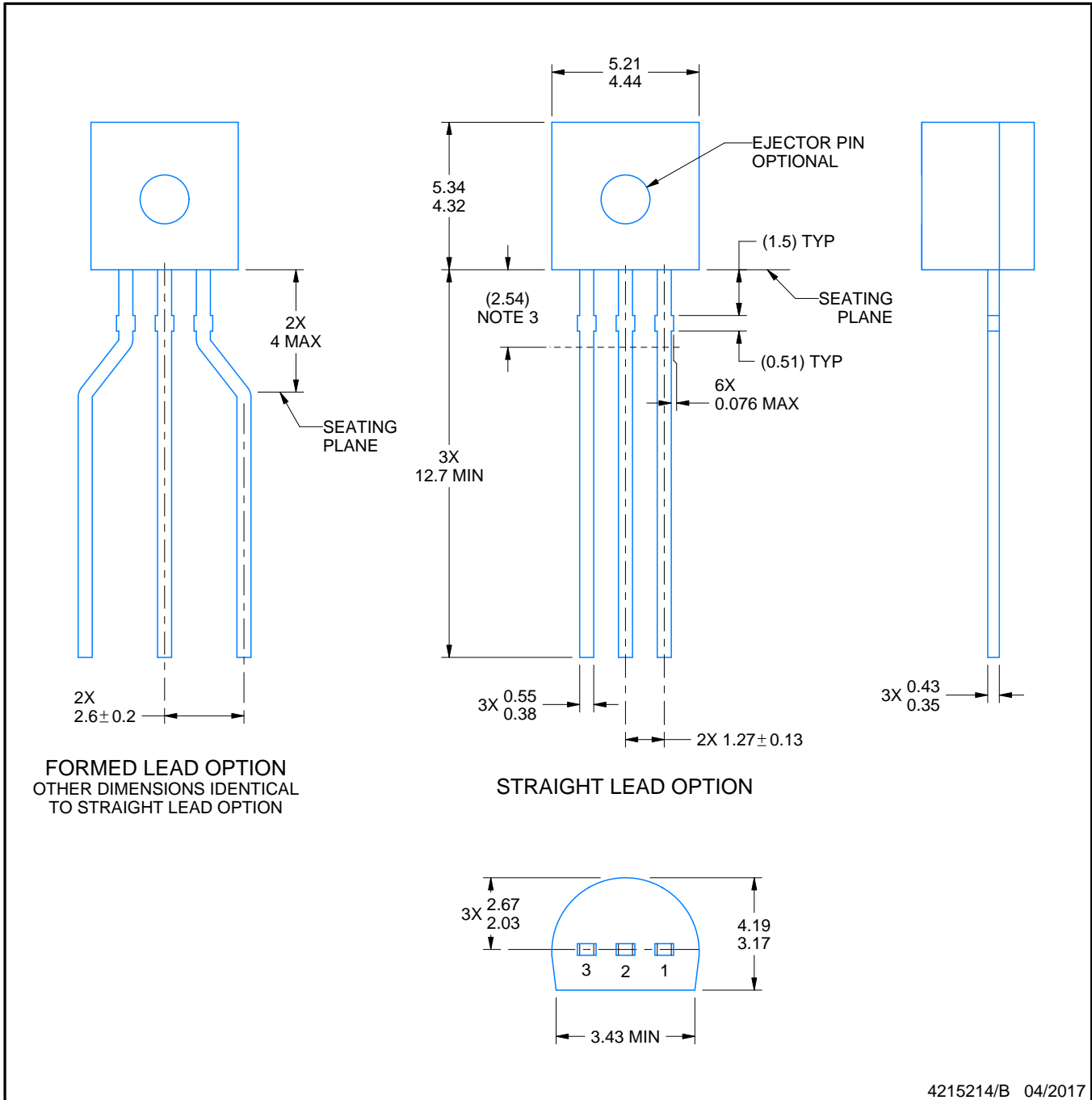
TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040001-2/F



4215214/B 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
  - a. Straight lead option available in bulk pack only.
  - b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.



LAND PATTERN EXAMPLE  
STRAIGHT LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X



LAND PATTERN EXAMPLE  
FORMED LEAD OPTION  
NON-SOLDER MASK DEFINED  
SCALE:15X

# TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

4215214/B 04/2017

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